

10/582251

AP3 Rec'd PCT/PTO 09 JUN 2006

**Application Data Sheet**

**Application Information**

Application Type::	Regular
Subject Matter::	National Phase
Suggested Group Art Unit::	N/A
CD-ROM or CD-R?::	None
Sequence submission?::	None
Computer Readable Form (CRF)?::	No
Title::	METHOD FOR CONSTRUCTING EMI SHIELDING AROUND A COMPONENT EMBEDDED IN A CIRCUIT BOARD
Attorney Docket Number::	0365-0678PUS1
Request for Early Publication?::	No
Request for Non-Publication?::	No
Total Drawing Sheets::	4
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

**Applicant Information**

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Finland
Status::	Full Capacity
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City of mailing address:: Helsinki  
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### **Correspondence Information**

Correspondence Customer Number:: 02292

### **Representative Information**

Representative Customer Number:: 02292

### **Domestic Priority Information**

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	National Stage of	PCT/FI2004/000752	12/09/04

### **Foreign Priority Information**

Country::	Application number::	Filing Date::	Priority Claimed::
Finland	20031796	12/09/03	Yes

### **Assignee Information**

Assignee name:: Aspocomp Technology Oy  
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